

Features

- $BV_{CEO} > -150V$
- $I_C = -600mA$ high Collector Current
- Ideal for Medium Power Switching or Amplification Applications
- Complementary PNP Type: DZT5551
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

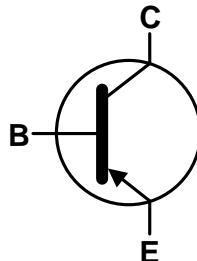
- Case: SOT223
- Case Material: Molded Plastic. "Green" Molding Compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.112 grams (Approximate)

Applications

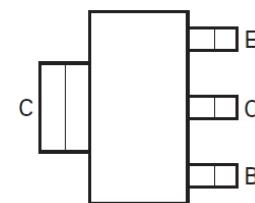
- Amplifiers
- Power Supplies



Top View



Device Symbol



Top View
Pin-Out

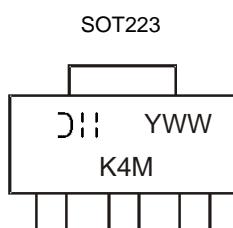
Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DZT5401-13	Standard	K4M	13	12	2,500

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



K4M = Product Type Marking Code
 DII = Manufacturer's Code Marking
 YWW = Date Code Marking
 Y = Last Digit of Year (ex: 7 = 2017)
 WW = Week Code (01 to 52)

Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-160	V
Collector-Emitter Voltage	V_{CEO}	-150	V
Emitter-Base Voltage	V_{EBO}	-6	V
Collector Current	I_C	-600	mA

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation @ $T_A = +25^\circ\text{C}$	(Note 5)	P_D	1
Thermal Resistance, Junction to Ambient @ $T_A = +25^\circ\text{C}$	(Note 5)	$R_{\theta JA}$	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

ESD Ratings (Note 6)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes:

- 5. For a device mounted with the collector lead on minimum recommended pad (MRP) layout 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

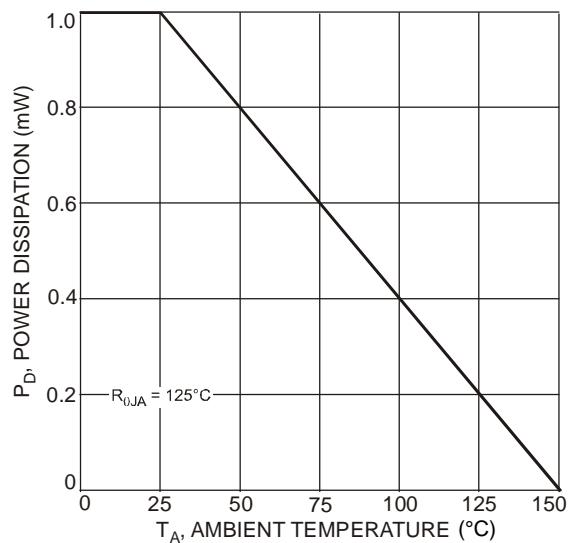


Fig. 1 Max Power Dissipation vs. Ambient Temperature

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV_{CBO}	-160	—	—	V	$I_C = -100\mu\text{A}, I_E = 0$
Collector-Emitter Breakdown Voltage (Note 7)	BV_{CEO}	-150	—	—	V	$I_C = -1\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	-6	—	—	V	$I_E = -10\mu\text{A}, I_C = 0$
Collector-Base Cut-off Current	I_{CBO}	—	—	-50	nA μA	$V_{\text{CB}} = -120\text{V}, I_E = 0$ $V_{\text{CB}} = -120\text{V}, I_E = 0, T_A = +150^\circ\text{C}$
Emitter-Base Cut-off Current	I_{EBO}	—	—	-50	nA	$V_{\text{EB}} = -3\text{V}, I_C = 0$
ON CHARACTERISTICS (Note 7)						
Collector-Emitter Saturation Voltage	$V_{\text{CE}(\text{SAT})}$	—	—	-0.2 -0.5	V	$I_C = -10\text{mA}, I_B = -1\text{mA}$ $I_C = -50\text{mA}, I_B = -5\text{mA}$
Base-Emitter Saturation Voltage	$V_{\text{BE}(\text{SAT})}$	—	—	-1.0	V	$I_C = -10\text{mA}, I_B = -1\text{mA}$ $I_C = -50\text{mA}, I_B = -5\text{mA}$
Static Forward Current Transfer Ratio	h_{FE}	50 60 50	—	— 240	—	$I_C = -1\text{mA}, V_{\text{CE}} = -5\text{V}$ $I_C = -10\text{mA}, V_{\text{CE}} = -5\text{V}$ $I_C = -50\text{mA}, V_{\text{CE}} = -5\text{V}$
SMALL SIGNAL CHARACTERISTICS						
Transition Frequency	f_T	100	—	300	MHz	$V_{\text{CE}} = -10\text{V}, I_C = -10\text{mA}, f = 100\text{MHz}$
Output Capacitance	C_{obo}	—	—	6	pF	$V_{\text{CB}} = -10\text{V}, f = 1\text{MHz}, I_E = 0$
Small Signal Current Gain	h_{FE}	40	—	260	—	$V_{\text{CE}} = -10\text{V}, I_C = -1.0\text{mA}, f = 1.0\text{kHz}$
Noise Figure	NF	—	—	8	dB	$V_{\text{CE}} = -5.0\text{V}, I_C = -200\mu\text{A}, R_S = 10\Omega, f = 1.0\text{kHz}$

Note: 7. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

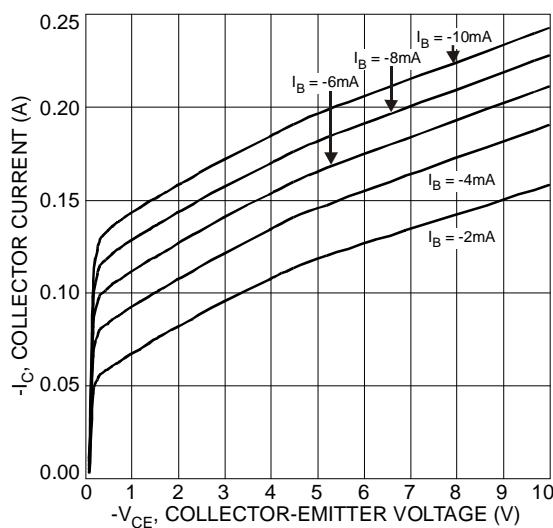
Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage

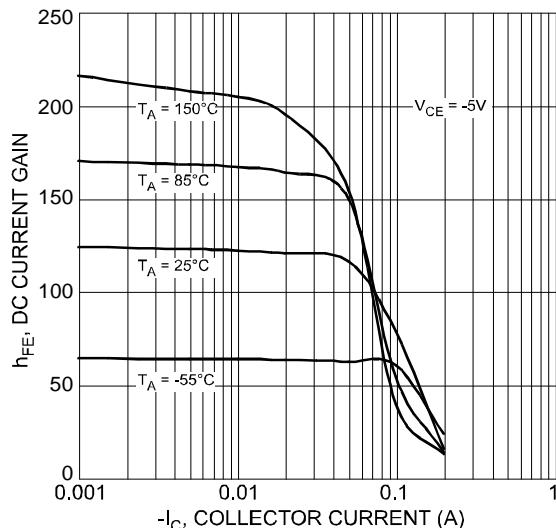


Fig. 3 Typical DC Current Gain vs. Collector Current

Typical Electrical Characteristics (Cont.)

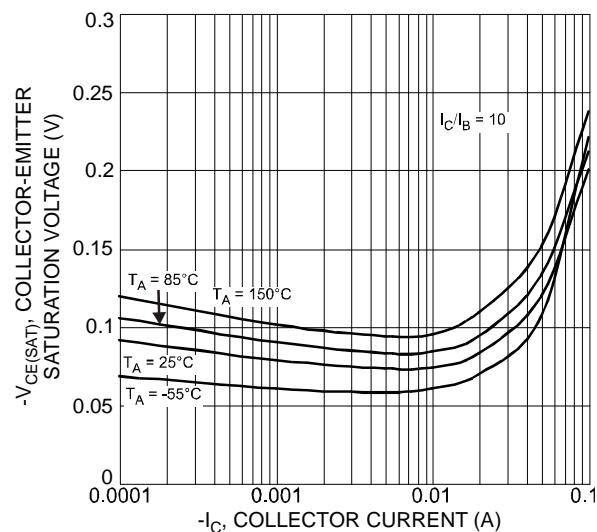


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

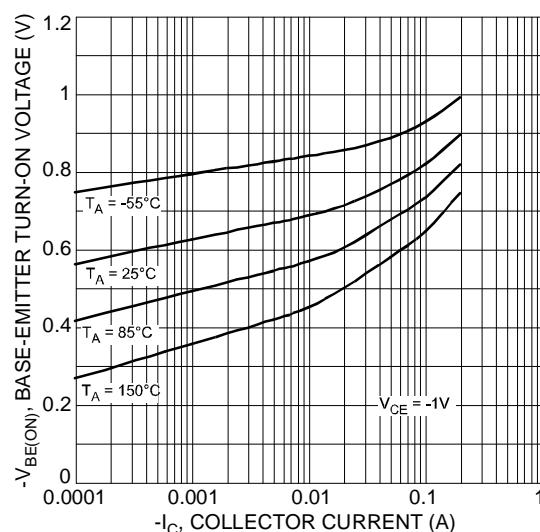


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

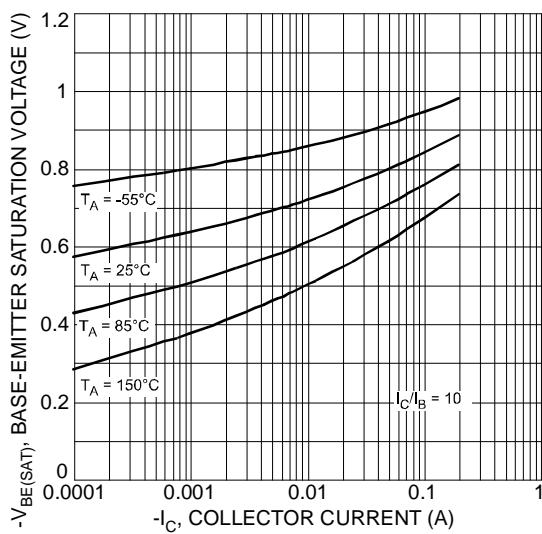


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

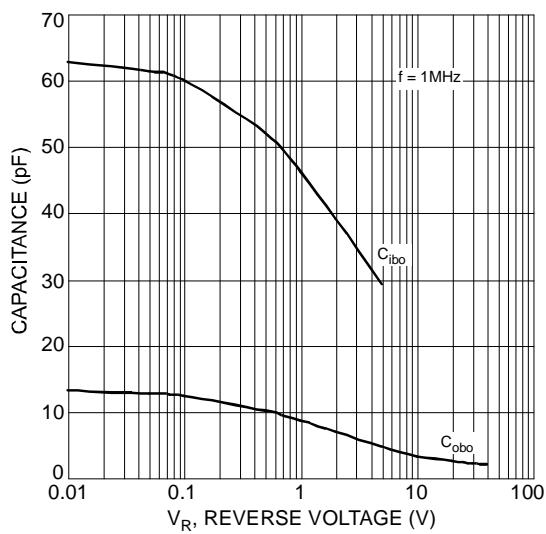


Fig. 7 Typical Capacitance Characteristics

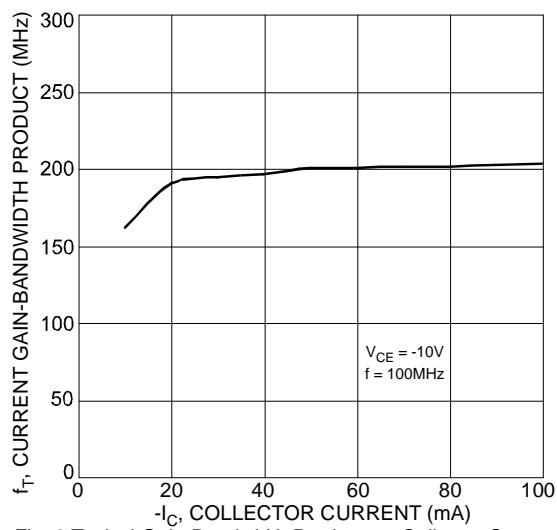
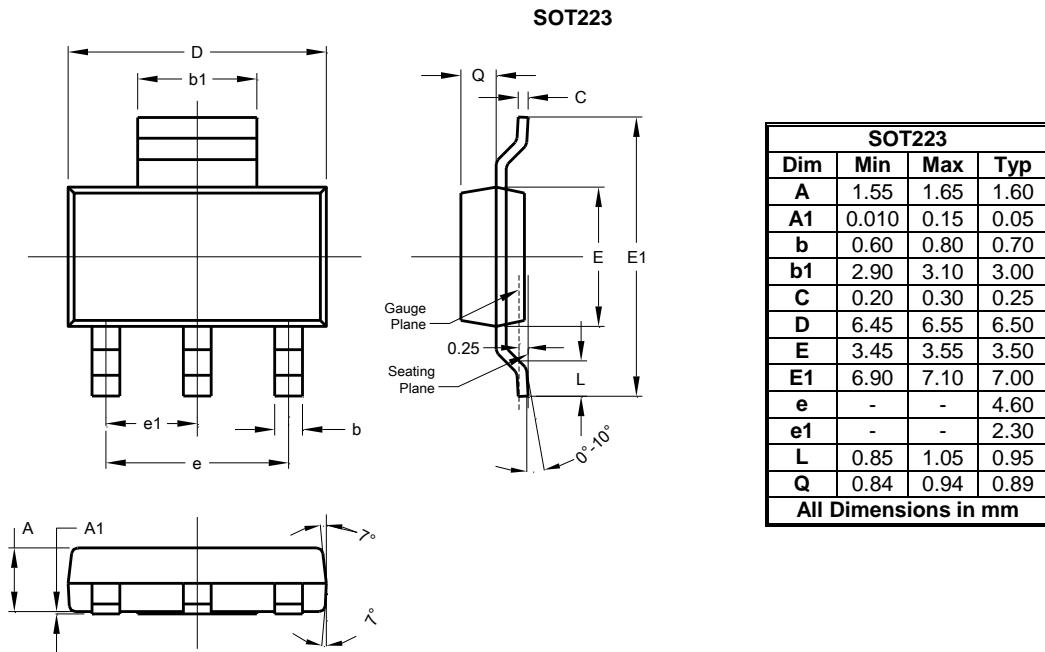


Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

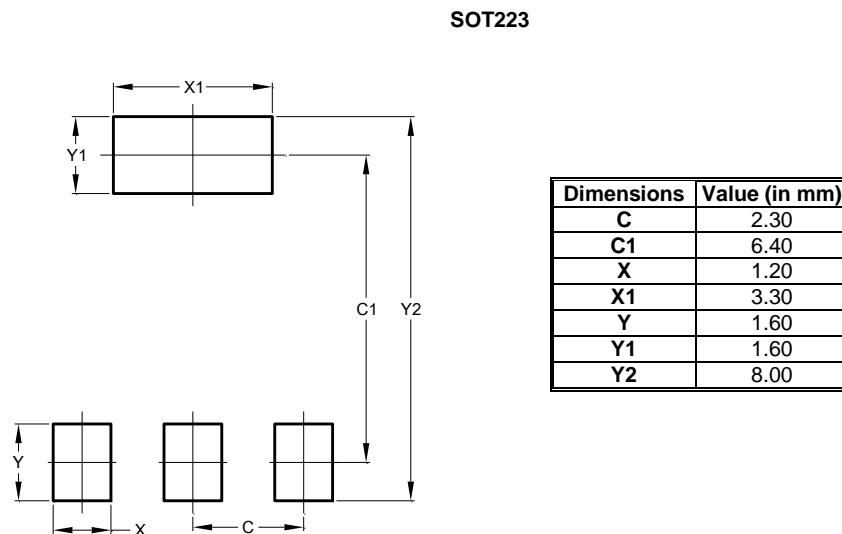
Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.

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